International Conference and Exhibition on

Device Packaging

www.imaps.org/devicepackaging

Radisson Fort McDowell Resort & Casino
Scottsdale/Fountain Hills, Arizona - USA
March 8 - 11, 2010

Sponsored by
IMAPS
International Microelectronics And Packaging Society
Bringing Together the Entire Microelectronics Supply Chain!

Abstract Deadline Extended:
December 14, 2009

Announcement and Call for Abstracts
Topical Workshop on
3D Packaging

This workshop is being held as a part of the Device Packaging Conference

Technical Chairs:

James J.-Q. Lu
Rensselaer Polytechnic Institute
Troy, NY 12180
Phone: 518-276-2909
luj@rpi.edu

Lee Smith
Amkor Technology, Inc.
Chandler, AZ 85248
Phone: 480-821-2408
lsmit@amkor.com

3D Packaging Organizing Committee:

Rozalia Beica, MAXIM Integrated Products, Inc.
Jeff Calvert, DOW Electronic Materials
Flynn Carson, STATS ChipPAC, Inc.
Kuan-Neng Chen, National Chiao Tung University
Kathy Cook, Alchimer S. A.
Yann Guillou, ST-Ericsson
Thorsten Matthias, EV Group
Bob Patti, Tezzaron Semiconductor
Peter Ramm, Fraunhofer IZM, Munich
Paul Siblerud, Semitool, Inc.
Nicolas Sillon, CEA LETI

3D Packaging Workshop Focus: The objective of the 3D Packaging Workshop is to have a unique forum that brings together scientists, engineers, manufacturing, academia, and business people from around the world who have been working in the area of 3D Packaging. This workshop has been specifically organized to allow for the presentation and debate of some of the latest and hottest technologies out there related to 3D Packaging technologies, as well as to bridge the gap between the back-end wafer-level 3D integration and 3D packaging, covering wire-bonded chip stack, system-in-packaging (SiP), package-on-package (PoP), through-silicon-via (TSV) based die-to-die (or chip), die-to-wafer, and wafer-to-wafer 3D approaches.

Attendees and presenters in the past have found that the 3D Packaging Workshop is a great opportunity to meet old colleagues and to form new relationships with people in the industry. If you are working in any area of electronics packaging or microelectronics, the Workshop on 3D packaging technologies would be well worth attending. **Abstracts are being requested on the following topics:**

- Stacked Die
- Stacked Packages
- PWB Embedded Device Technologies
- Memory Cubes
- Folded Flex
- Through Silicon Vias
- Vertical Interconnects
- Thin Wafer Processing
- Assembly Processes and Handling Issues
- Testing and Probing Challenges
- Failure Analysis and Reliability
- Simulation and Modeling
- Applications and System Requirements
- Thermal Management

The 3D Packaging Workshop will also be organizing an evening Panel Session on "Roadmap of 3D Integration and Packaging".

Those wishing to present in the 3D Packaging sector of the Device Packaging Conference must submit a 200-300 word abstract electronically **no later than December 14, 2009**, using the on-line submittal form at: www.imaps.org/abstracts.htm. No formal technical paper is required. A reproduction-ready two- to six-page concise summary with text (figures and graphs included if necessary) will be required for the abstract booklet on Friday, January 29, 2010. A post-conference CD containing the full presentation material as supplied by authors will be mailed 15 business days after the event to all attendees. Please contact Jackki Morris-Joyner by email at jmorris@imaps.org or by phone at 305-382-8433 if you have questions.

In addition, this year, the track Technical Chairs will be choosing select papers from the Conference for inclusion in a volume entitled "Advanced Microelectronic Packaging 2009". Participation is not mandatory, but we're sure many of you will want to participate in this highly exciting new concept. Papers not selected for this volume will, as always, have submission to the IMAPS online journal and submission to the annual IMAPS fall meeting as future options.

Device Packaging Exhibit and Technology Show: IMAPS will hold a concurrent exhibition for vendors and suppliers who support the many aspects of 3D Packaging. This venue features an ideal atmosphere to showcase your products and services to key decision making professionals in the industry. Full 8' by 10' exhibit spaces will be available. To reserve booth space please fill out the on-line submittal form before February 4, 2010 at: www.imaps.org/devicepackaging or contact Ann Bell by email at abell@imaps.org or by phone at 202-548-8717.

Device Packaging Professional Development Courses (PDCs): For those wishing to broaden their knowledge of device packaging, a selection of half-day courses will be offered on Monday, March 8th, preceding the technical conference. If you would like to participate as an instructor, please submit a description of your short course to Jackki Morris-Joyner by email at jmorris@imaps.org **no later than December 14, 2009.**